



Product Change Notification: CAAN-25HMUD609

Date:

13-Jul-2026

Product Category:

EL Backlight Driver ICs

Notification Subject:

CCB 7632 Final Notice: Qualification of ATP7 as an additional assembly site for HV852K7-G and HV853K7-G catalog part numbers (CPN) available in 10L WDFN (3x3x0.8mm) package.

Affected CPNs:

[CAAN-25HMUD609_Affected_CPN_07132026.pdf](#)

[CAAN-25HMUD609_Affected_CPN_07132026.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of ATP7 as an additional assembly site for HV852K7-G and HV853K7-G catalog part numbers (CPN) available in 10L WDFN (3x3x0.8mm) package.

Pre and Post Summary Changes:

	Pre Change	Post Change		Change (Yes/No)
Assembly Site	Carsem (Suzhou) (CARC)	Carsem (Suzhou) (CARC)	Amkor Technology Philippines (P3/P4), INC. (ATP7)	Yes

Wire Material	Au	Au	CuPdAu	Yes
Die Attach Material	QMI519 (PFAS-free)	QMI519 (PFAS-free)	AP4300 (PFAS-free)	Yes
Molding Compound Material	G770H D	G770H D	G631BQF	Yes
Lead-Frame Material	C194	C194	C194	No
Lead-Frame Paddle Size	104x75 mils	104x75 mils	106X75 mils	Yes
Lead-Frame Design	See Pre and Post Change Summary for Comparison			
DAP Surface Prep	Ag spot	Ag spot	Ring Ag	Yes

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve on time delivery performance by qualifying ATP7 as an additional assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: 02 August 2026 (date code: 2631)

Note Below EFSD: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	May 2025					>	July 2026				August 2026				
Work Week	18	19	20	21	22		27	28	29	30	31	32	33	34	35
Initial PCN Issue Date					X										
Qual Report Availability									X						
Final PCN Issue Date									X						
Estimated Implementation Date											X				

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: May 28, 2025: Issued initial notification.

July 13, 2026: Issued final notification. Added the "Change (Yes/No)" column to the Pre- and Post-Change Summary table and noted that the die attach material is PFAS-free. Attached the Qualification Report. Provided estimated first ship date to be on August 2, 2026.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[PCN_CAAN-25HMUD609_Pre and Post Change_Summary.pdf](#)

[PCN_CAAN-25HMUD609-Qual Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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